



VMDSEMI

**VFTA010R052NA**

**Datasheet**



VMDSEMI

## General Description

## Symbol

|               |                    |       |
|---------------|--------------------|-------|
| $V_{(BR)DSS}$ | $R_{DS(ON)_{max}}$ | $I_D$ |
| 100V          | 5.2mΩ@10V          | 125A  |

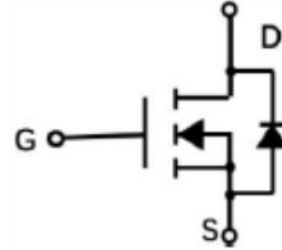


Figure 1 Symbol of VFTA010R052NA

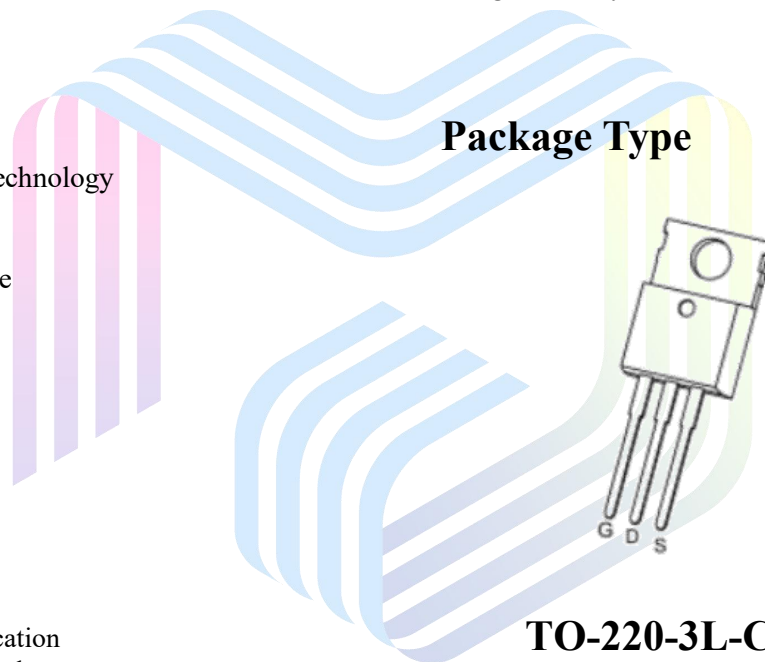
## Features

- Split Gate Trench Technology
- Low  $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested
- 100%  $\Delta V_{DS}$  Tested

## Package Type

## Application

- DC/DC Converter
- Synchronous Rectification
- High-Frequency Switch



**TO-220-3L-C**

Figure 2 Package Type of VFTA010R052NA

## Ordering Information

| Product Name  | Package     |
|---------------|-------------|
| VFTA010R052NA | TO-220-3L-C |

**Absolute Maximum Ratings** ( $T_A = 25\text{ °C}$ , unless otherwise specified)

| Parameter                                       | Symbol    | Rating     | Unit |
|---|-----------|------------|------|
| Drain-Source Voltage                            | $V_{DSS}$ | 100        | V    |
| Gate-Source Voltage                             | $V_{GSS}$ | $\pm 20$   | V    |
| Continuous Drain Current <sup>Note1</sup>       | $I_D$     | 125        | A    |
| Pulsed Drain Current <sup>Note2</sup>           | $I_{DM}$  | 500        |      |
| Avalanche Current <sup>Note3</sup>              | $I_{AS}$  | 18         |      |
| Single Pulsed Avalanche Energy <sup>Note3</sup> | $E_{AS}$  | 81         | mJ   |
| Total Power Dissipation <sup>Note5</sup>        | $P_D$     | 271        | W    |
| Junction Temperature                            | $T_J$     | 150        | °C   |
| Storage Temperature                             | $T_{STG}$ | -55 to 150 | °C   |

**Thermal Resistance**

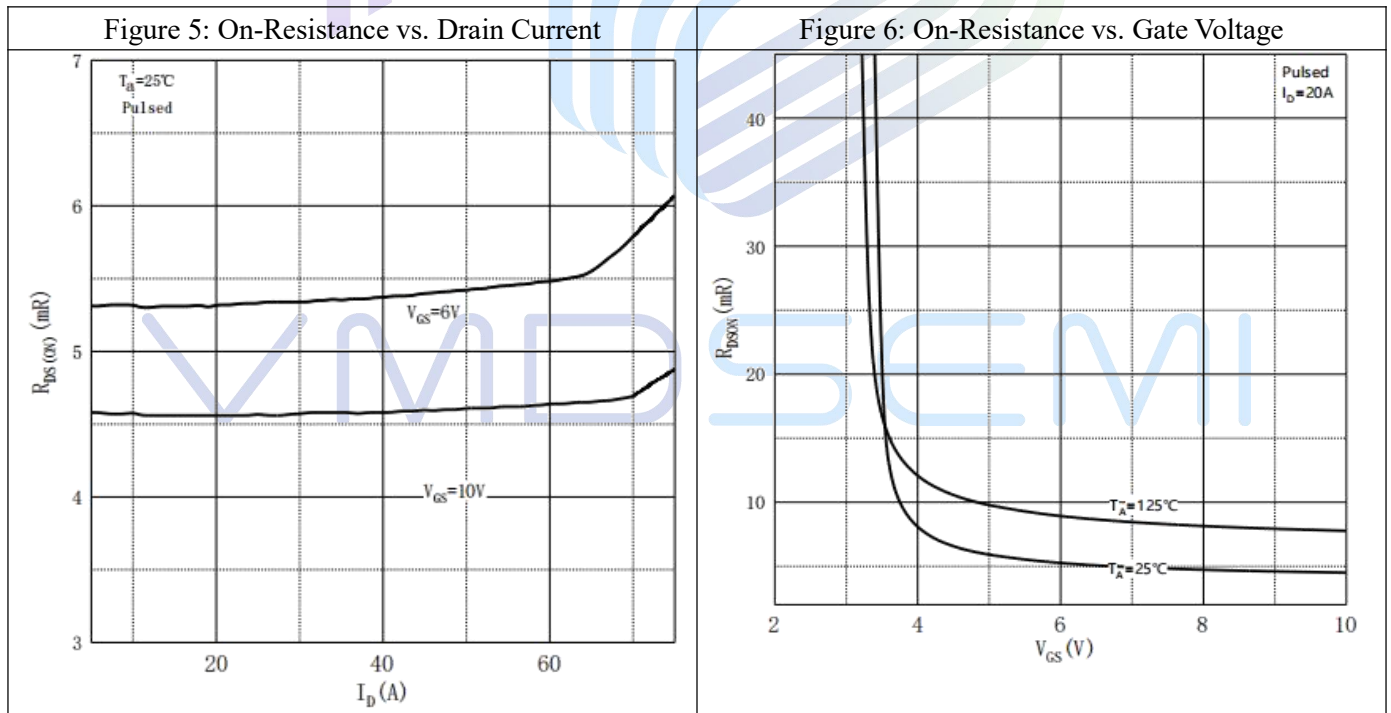
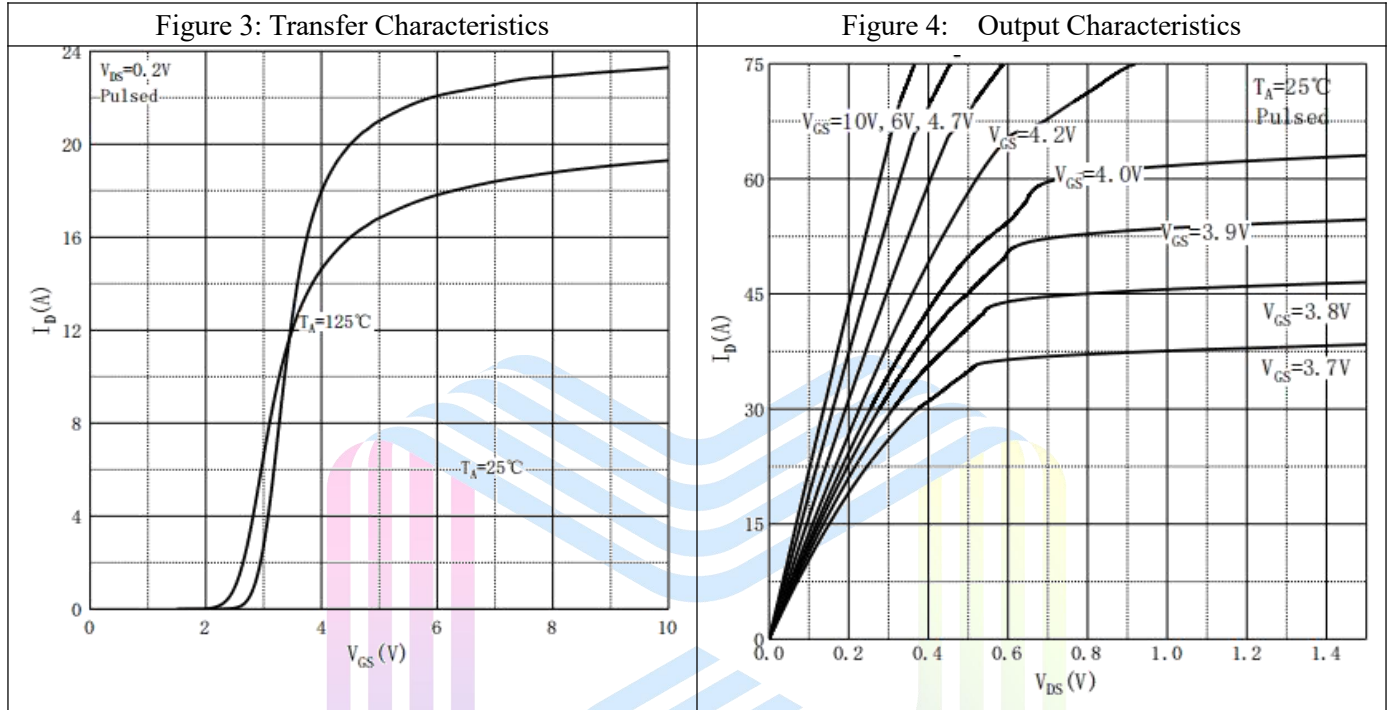
| Parameter  | Symbol          | Min | Typ  | Max | Unit |
|--|-----------------|-----|------|-----|------|
| Thermal Resistance, Junction-to-Ambient <sup>Note6</sup> | $R_{\theta JA}$ |     | 60   |     | °C/W |
| Thermal Resistance, Junction-to-Case                     | $R_{\theta JC}$ |     | 0.46 |     | °C/W |

**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)

| Parameter  | Symbol       | Test Conditions               | Min | Typ  | Max       | Unit    |
|--|--------------|-------------------------------|-----|------|-----------|---------|
| <b>Statistic Characteristics</b>                   |              |                               |     |      |           |         |
| Drain-Source Breakdown Voltage                     | $BV_{DSS}$   | $V_{GS}=0V, I_D=250\mu A$     | 105 |      |           | V       |
| Zero Gate Voltage Drain Current                    | $I_{DSS}$    | $V_{DS}=100V, V_{GS}=0V$      |     |      | 1         | $\mu A$ |
| Gate-Body Leakage Current                          | $I_{GSS}$    | $V_{GS} = \pm 20V, V_{DS}=0V$ |     |      | $\pm 100$ | nA      |
| Gate Threshold Voltage <sup>Note4</sup>            | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 1.0 | 2.0  | 3.0       | V       |
| Static Drain-Source On-Resistance <sup>Note4</sup> | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=20A$         |     | 4.3  | 5.2       | mΩ      |
| Forward Transconductance <sup>Note4</sup>          | $g_{FS}$     | $V_{DS}=5V, I_D=20A$          | 20  |      |           | S       |
| <b>Dynamic Characteristics</b>                     |              |                               |     |      |           |         |
| Input Capacitance                                  | $C_{ISS}$    | $V_{DS}=45V$                  |     | 3465 |           | pF      |
| Output Capacitance                                 | $C_{OSS}$    | $V_{GS}=0V$                   |     | 674  |           | pF      |
| Reverse Transfer Capacitance                       | $C_{RSS}$    | $f=1MHz$                      |     | 6.8  |           | pF      |
| Total Gate Charge                                  | $Q_g$        | $V_{DS}=50V$                  |     | 57.2 |           | nC      |
| Gate-Source Charge                                 | $Q_{gs}$     | $V_{GS}=10V$                  |     | 5.8  |           |         |
| Gate-Drain Charge                                  | $Q_{gd}$     | $I_D=20A$                     |     | 3.1  |           |         |
| Gate Resistance                                    | $R_g$        | $f=1MHz, \text{Open drain}$   |     | 1.2  |           | Ω       |
| <b>Switching Parameters</b>                        |              |                               |     |      |           |         |
| Turn-on Delay Time                                 | $t_{d(on)}$  | $V_{DD}=50V$                  |     | 21   |           | ns      |
| Turn-on Rise Time                                  | $t_r$        | $V_{GS}=10V$                  |     | 22   |           |         |
| Turn-off Delay Time                                | $t_{d(off)}$ | $R_L=2.5\Omega$               |     | 58   |           |         |
| Turn-off Fall Time                                 | $t_f$        | $R_G=3\Omega$                 |     | 20   |           |         |
| <b>Diode Characteristics</b>                       |              |                               |     |      |           |         |
| Diode Forward Voltage <sup>Note4</sup>             | $V_{SD}$     | $V_{GS}=0V, I_S=20A$          |     |      | 1.2       | V       |

Notes :

- The maximum current rating is limited by package. And device mounted on a large heatsink.
- Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- $E_{AS}$  condition:  $V_{DD} = 50V, V_{GS} = 10V, L = 0.5mH, R_G=25\Omega$  Starting  $T_J = 25^\circ\text{C}$ .
- Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ\text{C}$ . And device mounted on a large heatsink
- Device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

**Typical Performance Characteristics**


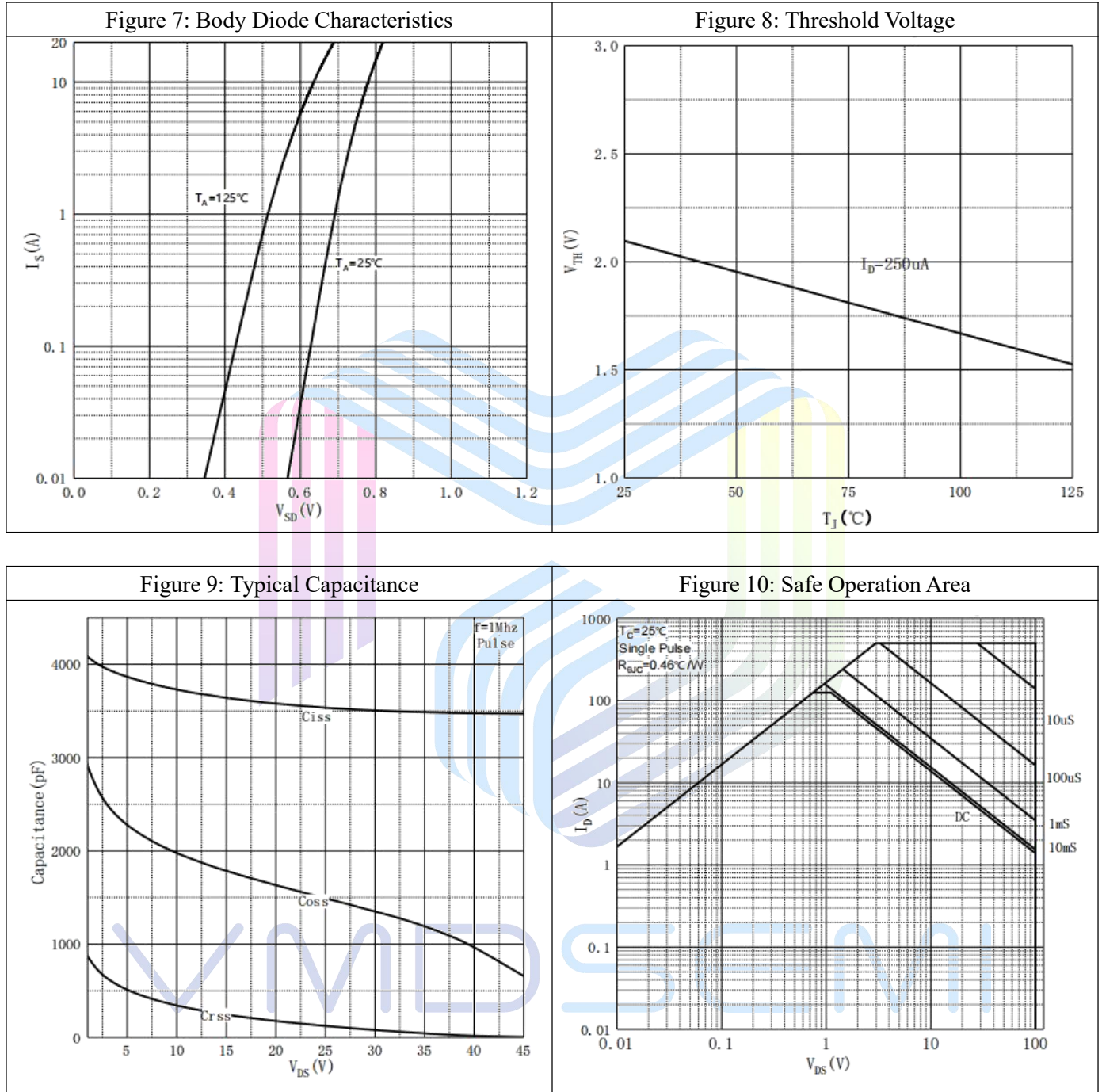
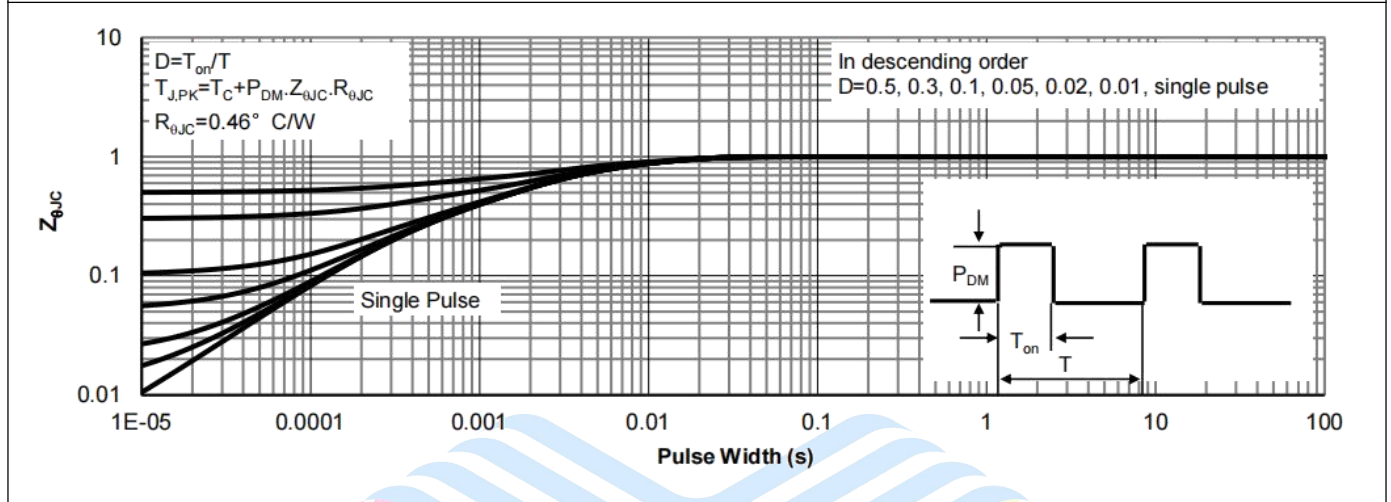
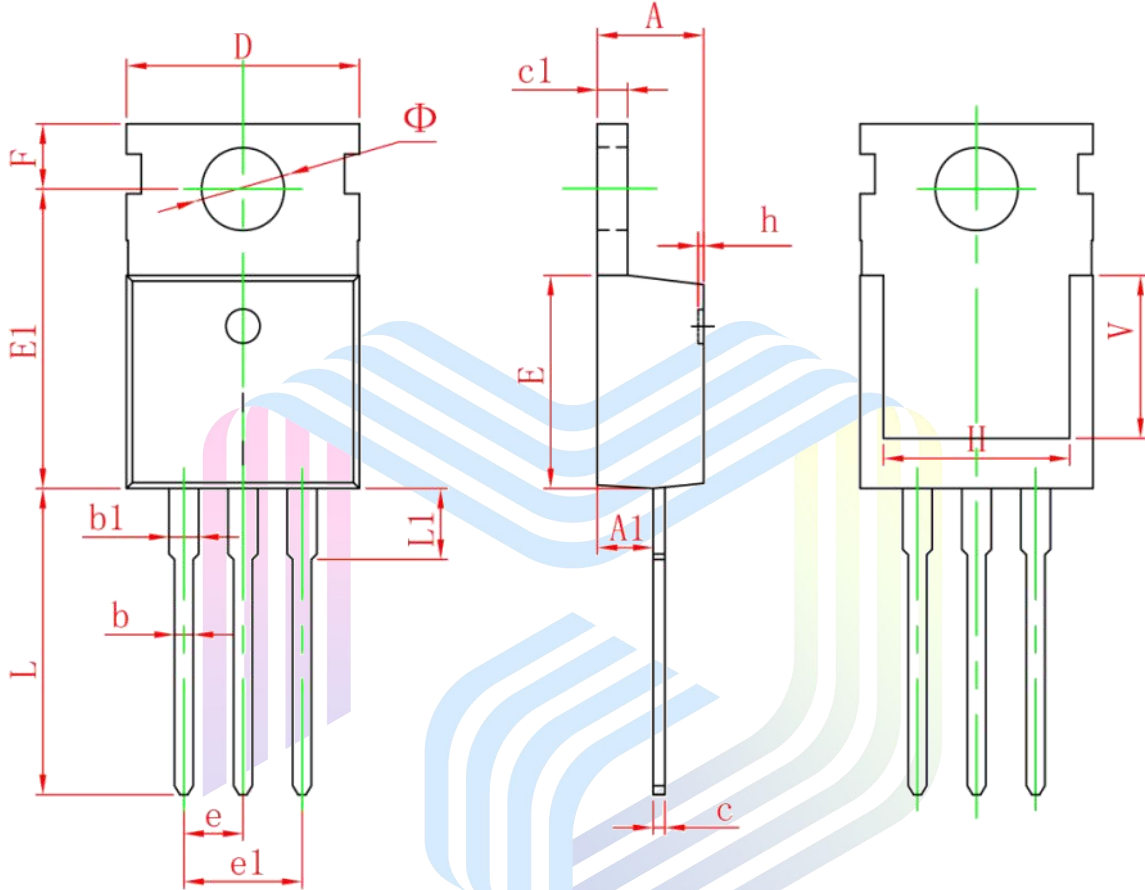


Figure 11: Normalized Maximum Transient Thermal Impedance




# VMDSEMI

**Mechanical Dimensions:**
**TO-220-3L-C Package Information**


| Symbol | Dimensions In Millimeters |        | Dimensions In Inches |       |
|--------|---------------------------|--------|----------------------|-------|
|        | Min.                      | Max.   | Min.                 | Max.  |
| A      | 4.400                     | 4.600  | 0.173                | 0.181 |
| A1     | 2.250                     | 2.550  | 0.089                | 0.100 |
| b      | 0.710                     | 0.910  | 0.028                | 0.036 |
| b1     | 1.170                     | 1.370  | 0.046                | 0.054 |
| c      | 0.330                     | 0.650  | 0.013                | 0.026 |
| c1     | 1.200                     | 1.400  | 0.047                | 0.055 |
| D      | 9.910                     | 10.250 | 0.390                | 0.404 |
| E      | 8.950                     | 9.750  | 0.352                | 0.384 |
| E1     | 12.650                    | 13.050 | 0.498                | 0.514 |
| e      | 2.540TYP                  |        | 0.100TYP             |       |
| e1     | 4.980                     | 5.180  | 0.196                | 0.204 |
| F      | 2.650                     | 2.950  | 0.104                | 0.116 |
| H      | 7.900                     | 8.100  | 0.311                | 0.319 |
| h      | 0.000                     | 0.300  | 0.000                | 0.012 |
| L      | 12.900                    | 13.400 | 0.508                | 0.528 |
| L1     | 2.850                     | 3.250  | 0.112                | 0.128 |
| V      | 6.900REF                  |        | 0.272REF             |       |
| Φ      | 3.400                     | 3.800  | 0.134                | 0.150 |



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